

Please add the following claims:

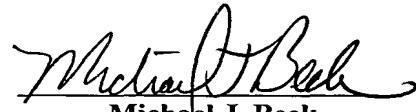
31. A method of assembling a multi dynode device comprising:  
placing a plurality of dynode plates onto an assembly frame in a stacked  
relationship; and  
securing the stacked plurality of dynode plates together before removing the  
stack from the assembly frame,  
wherein the assembly frame comprises inclined alignment pins, the inclined  
alignment pins defining a lateral offset amount, the plurality of dynode plates being  
laterally offset from one another in the stacked relationship by the lateral offset  
amount.
32. The method of assembling of Claim 31, wherein each dynode plate  
comprises a plurality of apertures, the apertures of each dynode plate being laterally  
offset from the apertures in adjacent dynode plates in the stacked relationship.
33. The method of assembling of Claim 31, wherein placing comprises guiding  
and orienting the dynode plates in the stacked relationship with respect to one another  
on the assembly frame using the inclined alignment pins.
34. The method of assembling of Claim 31, further comprising alternately  
placing a spacer ring of a plurality of spacer rings between adjacent dynode plates of  
the plurality, wherein securing the stacked plurality comprises securing together the  
alternately stacked plurality of dynode plates and spacer rings.
35. The method of assembling of Claim 31, further comprising applying a  
passive device material to a periphery of a surface of the dynode plates, the surface  
being the surface that faces an adjacent dynode plate when subsequently placed in the  
stacked relationship, the applied passive device material providing an integral spacer  
ring between adjacent dynode plates in the stacked relationship, the passive device  
material comprising one or both of a resistive material and a capacitive material, the

applied passive device material providing an integral bias network to the secured  
stacked plurality.

Respectfully submitted,

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